





## HY400 Series

**Thermal Interface material** 

## Special Design for Electronic Components Heat Transfer

| Item                    | HY410                        |
|-------------------------|------------------------------|
| Colour                  | white                        |
| Thermal Conductivity    | 1.42 W/m-k                   |
| Thermal Impedance       | <0.252 °C-in <sup>2</sup> /W |
| Specific Gravity        | 2.2 g/cm <sup>3</sup>        |
| Thixotropic Index       | 390 ±1.0mm                   |
| Moment Bore Temperature | -50 ~ +280°C                 |
| Operation Temperature   | -30 ~ +230°C                 |

## Ingredients

| Silicone Compounds    | 35%                   |
|-----------------------|-----------------------|
| Carbon Compounds      | 45%                   |
| Metal Oxide Compounds | 20%                   |
| Packaging             | Siring 25g, Tube 100g |

## Applications

for CPU, VGA, LED Chipset and other PC components Heat sink's, high power transistors, resistors and other electronic components

Compliance with RoHS REACH PFOS requirements Executive standard: Q/HYTG 001-2017

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